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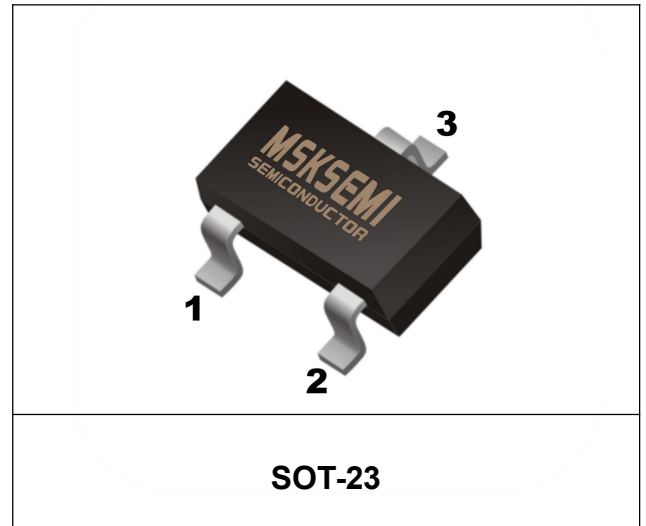
PLED

BAS70/-04/-05/-06

Product specification

Features

- Low turn-on voltage
- Fast switching
- Also available in lead free version



Reference News

Pin Configuration				
Marking				
P/N	BAS70Marking:73	BAS70-04Marking:74	BAS70-05Marking:75	BAS70-06Marking:76

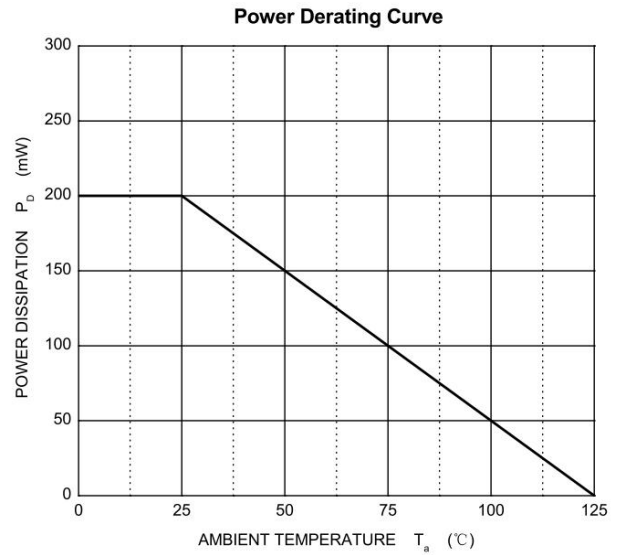
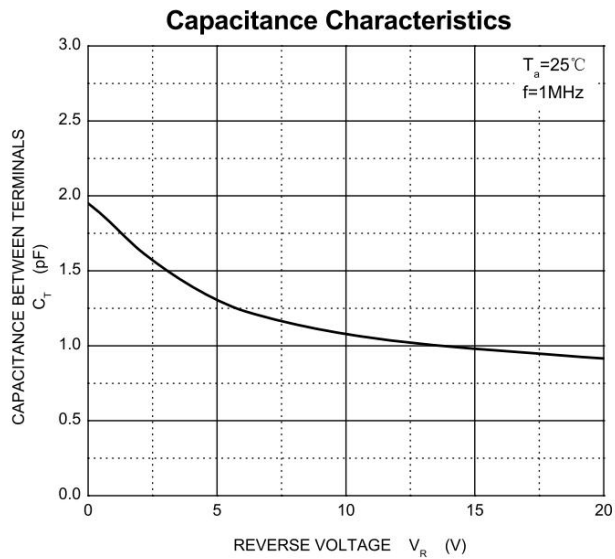
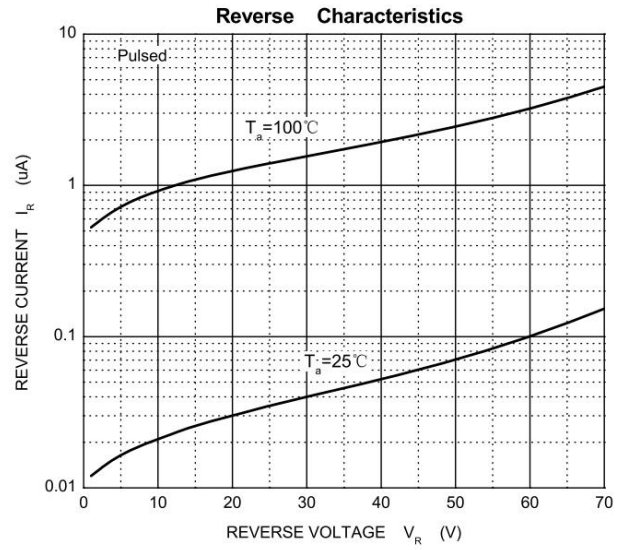
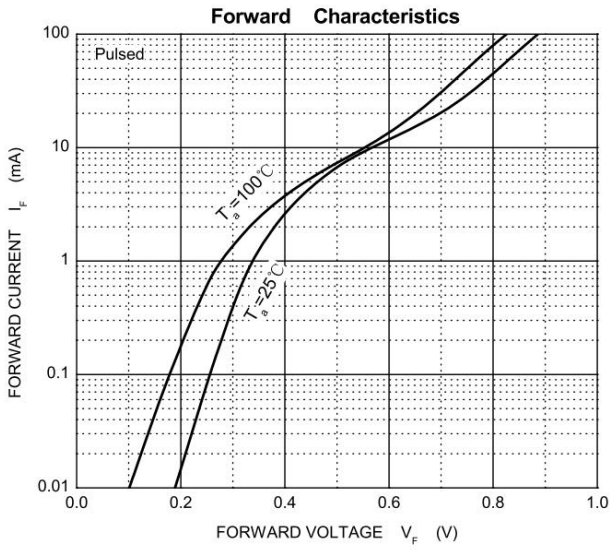
MAXIMUM RATINGS@Ta=25°C

Symbol	Parameter	Value	Unit
V _R	DC Voltage	70	V
I _F	Forward Continuous Current	70	mA
I _{FSM}	Non-Repetitive Peak Forward Surge Current @ t=8.3ms	100	mA
P _D	Power Dissipation	200	mW
R _{9JA}	Thermal Resistance Junction to Ambient	500	°C/W
T _J	Operating Junction Temperature Range	-40~+125	°C
T _{stg}	Storage Temperature Range	-55~+150	°C

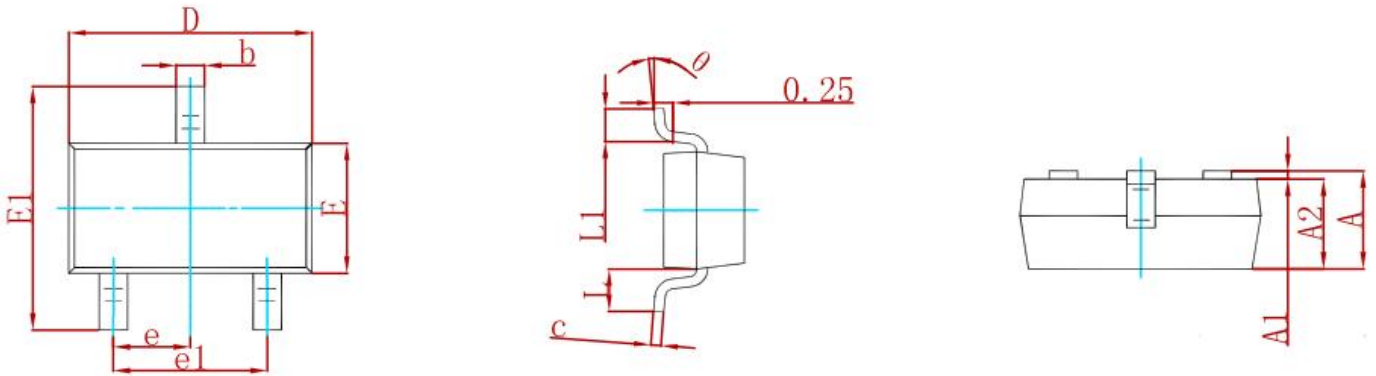
ELECTRICAL CHARACTERISTICS(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	V _(BR)	I _R = 10 μA	70		V
Reverse voltage leakage current	I _R	V _R = 50V		100	nA
Forward voltage	V _F	I _F = 1mA I _F = 15mA		410 1000	mV
Diode capacitance	C _D	V _R = 0V f = 1MHz		2	pF
Reverse recovery time	t _{rr}	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω		5	ns

ELECTRICAL CHARACTERISTICS CURVE

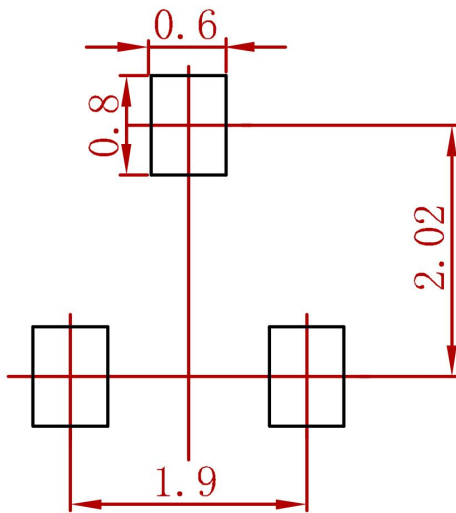


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS70/-04/-05/-06	SOT-23	3000

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